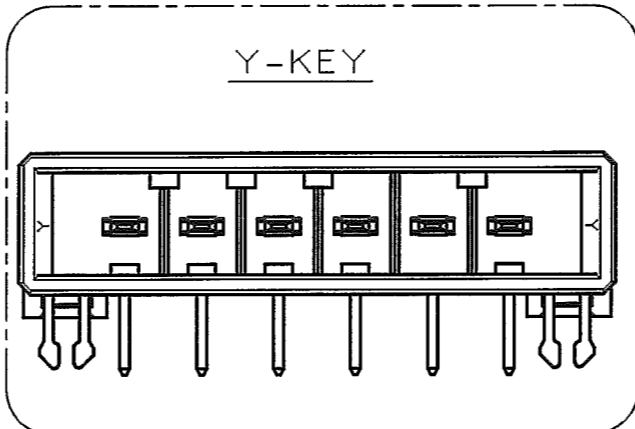
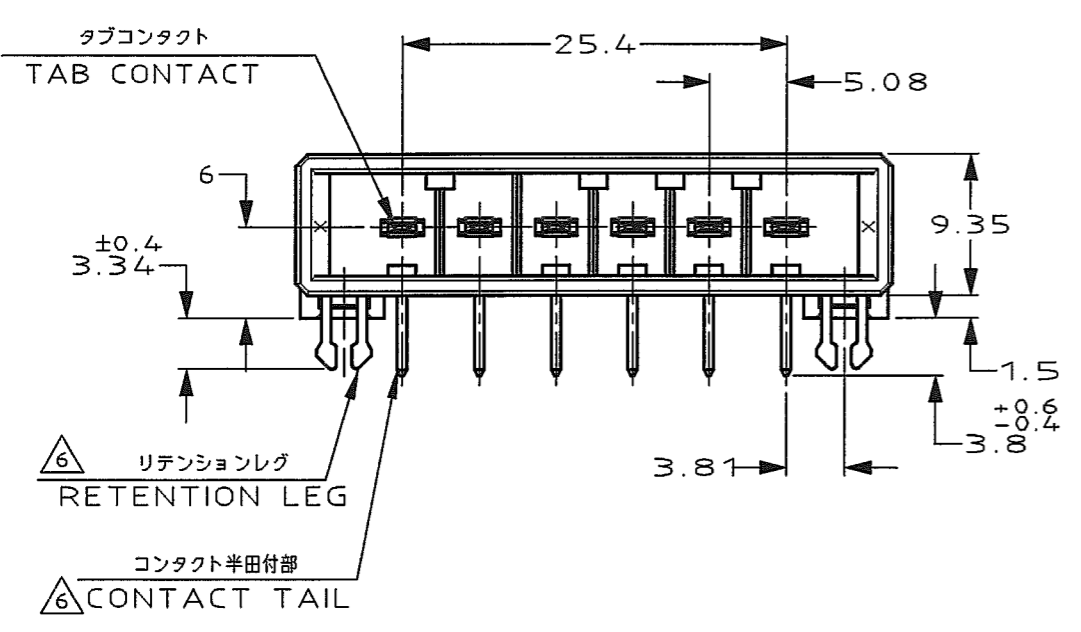
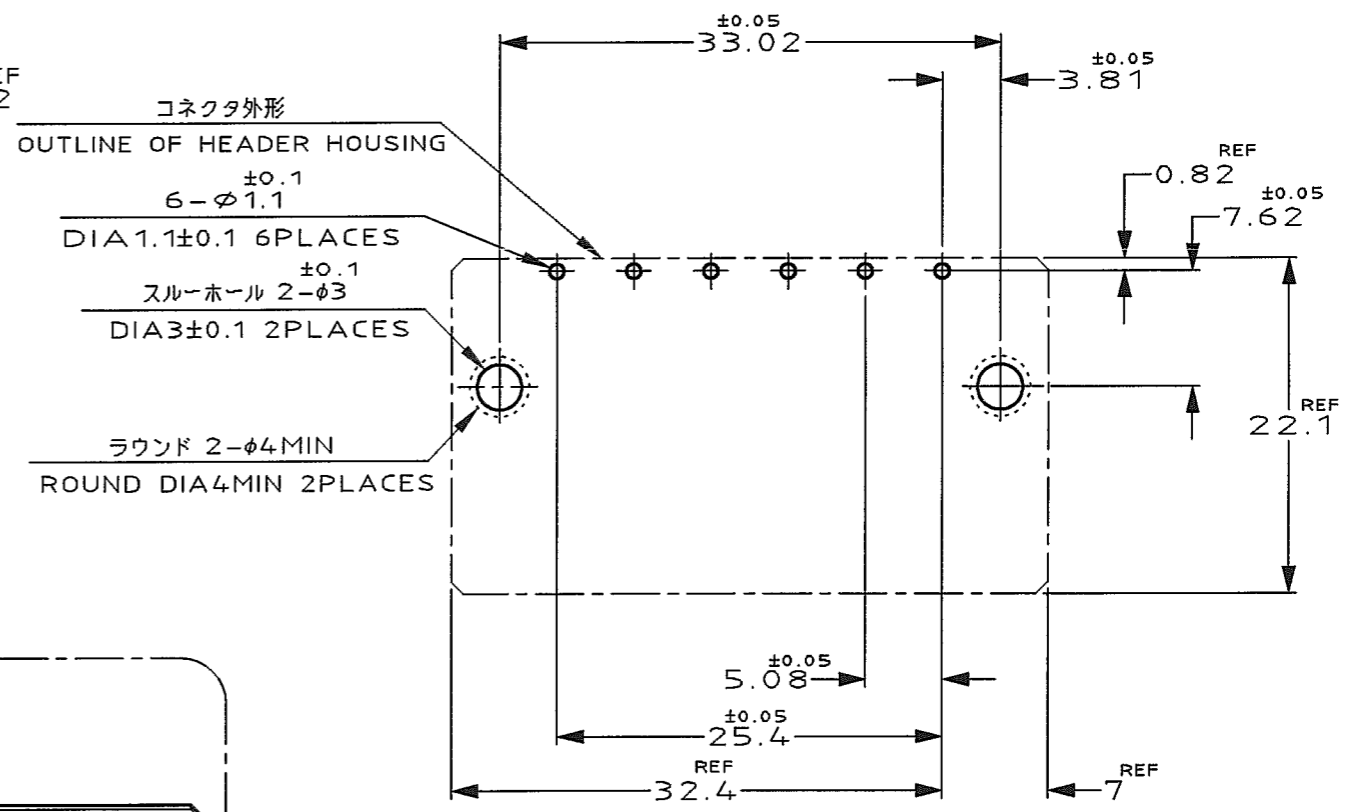
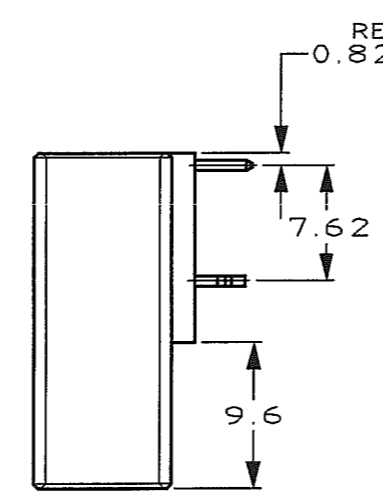
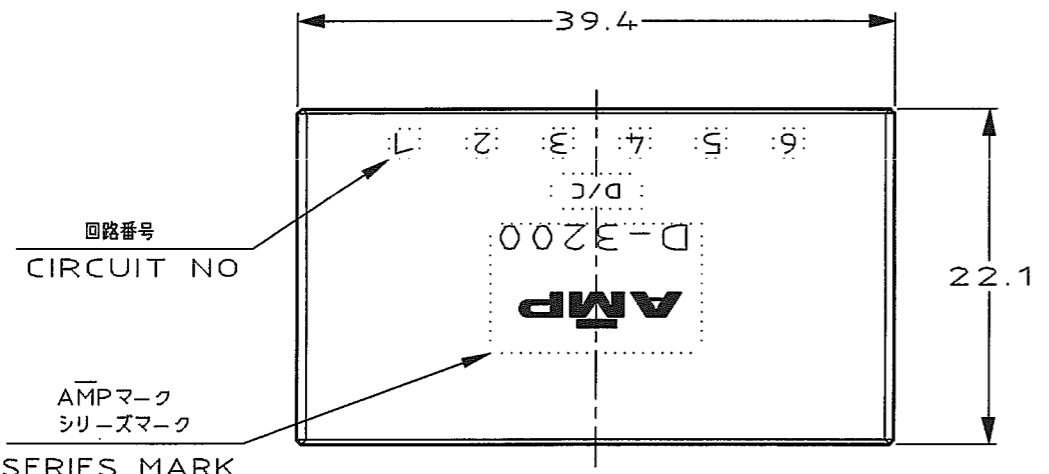


NUMBER 316131
METRIC
3rd ANGLE PROJECTION



推奨基板取付け穴寸法
PC 基板厚: 1.6±0.1
(非累積公差)
(コネクタ搭載面)

RECOMEND PC BOARD HOLE PATTERN
PC BOARD THICKNESS: 1.6±0.1
(NOT ACCUMULATE TOLERANCE)
(CONNECTOR MOUNT SIDE)

- NOTES
- MATERIAL: HOUSING: GLASS FILLED THERMO PLASTIC, POLYESTER
CONTACT: COPPER ALLOY
RETENTION LEG: COPPER ALLOY
 - FINISH (CONTACT AREA): 0.38 μm MIN GOLD PLATING OVER Ni PLATING
 - FINISH (CONTACT AREA): 0.76 μm MIN GOLD PLATING OVER Ni PLATING
 - FINISH (CONTACT AREA): 2.0 μm MIN TIN PLATED OVER NICKEL
 - FINISH (RETENTION LEG): TIN-LEAD PLATED (CONTACT TAIL) OVER NICKEL
 - FINISH (RETENTION LEG): TIN PLATED (CONTACT TAIL) OVER NICKEL

- 注記
- 材料: ハウジング: ガラス入り熱可塑性ポリエステル樹脂
コンタクト: 銅合金
リテンションレグ: 銅合金
 - めっき: コンタクト: 全面Ni下地
接触部: 0.38 μm MIN金めっき
 - めっき: コンタクト: 全面Ni下地
接触部: 0.76 μm MIN金めっき
 - めっき: コンタクト: 全面Ni下地
接触部: 2.0 μm MINスズめっき
 - めっき: リテンションレグとコンタクト半田付部
ニッケル下地の土に半田めっき
 - めっき: リテンションレグとコンタクト半田付部
ニッケル下地の土にスズめっき

△6	△4	2-316131-5	Y
△6	△3	2-316131-3	Y
△6	△2	2-316131-2	Y
△6	△4	1-316131-5	X
△6	△3	1-316131-3	X
△6	△2	1-316131-2	X
(FINISH)		製品番号 (PART NO.)	KEY

B	REVISED (FJD0-0039-03)	T S	S.M	25/3/93
A	REVISED (FJD0-0114-03)	T S	SM	25/3/93
0	RELEASED (FJ00-2557-95)	KI	YI	31/7/95
LTR	REVISION RECORD	DR	CHK	DATE

WIRE RANGE		INSULATION DIA		NAME	
mm² (AWG -)		mmφ		5 POS SINGLE ROW HORIZONTAL HDR ASS'Y FOR DYNAMIC D-3200	
MATERIAL SEE NOTE 注記参照		FINISH SEE NOTE 注記参照		一般公差 (GENERAL TOLERANCE)	
DR. 26/JUL/95 K.IKEDA		DE. 26/JUL/95 K.IKEDA		100μm : ±0.2	SIZE A3
CHK. 31/JUL/95 Y.ISHIKAWA		APP. 31/JUL/95 S.MANABE		100μm 300μm : ±0.3	LOC J
				300μm 1000μm : ±0.4	NUMBER C-316131
				角度 : ±3'	SCALE 2-1

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REVISION RECORD		SCALE	REV.
		2-1	B
		SHEET 1 OF 1	